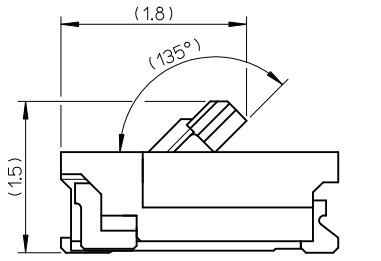
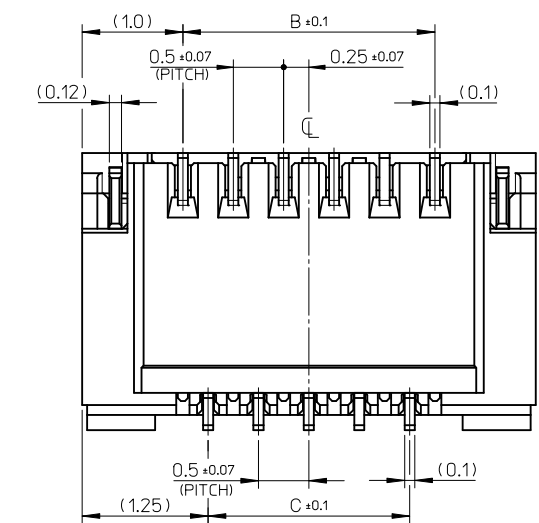
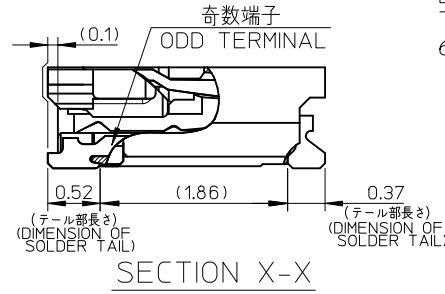
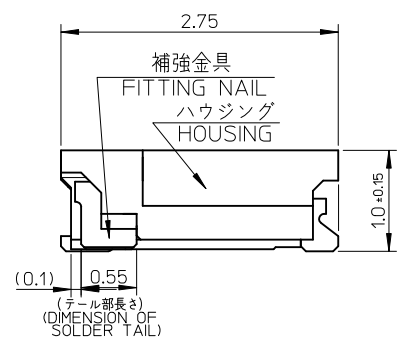
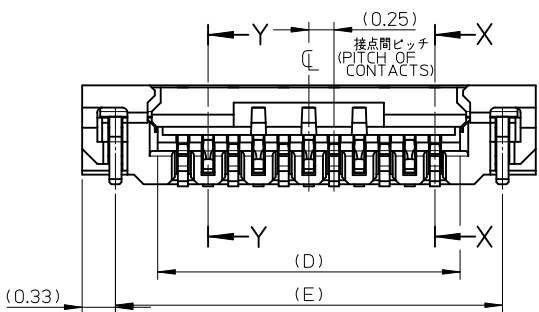


注記 NOTES

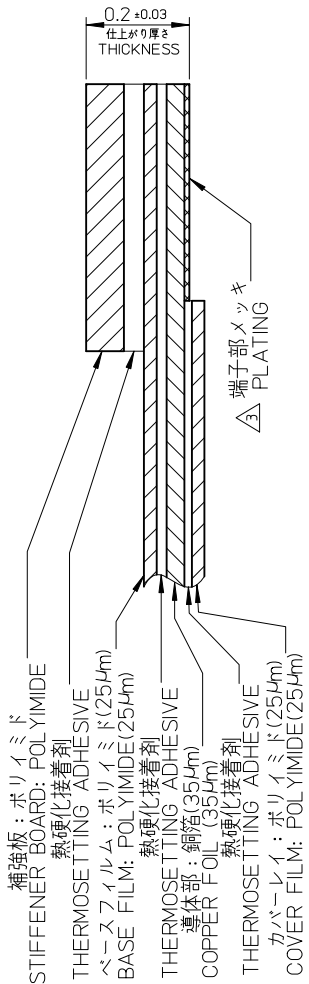
1. 使用材料 MATERIALS
 - ハウジング : 耐熱性樹脂(UL94V-0、ベージュ)
 - アクチュエータ : 耐熱性樹脂(UL94HB、黒色)
 - 奇数端子 : 銅合金、ニッケル下地、金メッキ
 - 偶数端子 : 銅合金、ニッケル下地、金メッキ
 - 補強金具 : 銅合金、ニッケル下地、スズメッキ
 - HOUSING : G.F. HEAT RESISTANCE PLASTIC (BEIGE)
 - ACTUATOR : G.F. HEAT RESISTANCE PLASTIC (BLACK)
 - ODD TERMINAL : COPPER ALLOY, Gold OVER Nickel PLATING
 - EVEN TERMINAL : COPPER ALLOY, Gold OVER Nickel PLATING
 - FITTING NAIL : COPPER ALLOY, Tin OVER Nickel PLATING
- △ 端子、補強金具のコプラナリティーは 0.1 以下とする
COPLANARITY OF SOLDER TAILS AND FITTING NAILS : 0.1MAX.
3. 一般公差: ±0.3
GENERAL TOLERANCES: ±0.3
 - △ アクチュエータの図示箇所にゲート逃げの凹みがあります
THERE ARE DENT SHAPES AT ACTUATOR FOR MOLDING GATE
 5. ELV 及び RoHS 適合品
ELV AND ROHS COMPLIANT
 6. 塩素系・臭素系難燃剤非使用
CHLORINATED AND BROMINATED FLAME RETARDANTS FREE



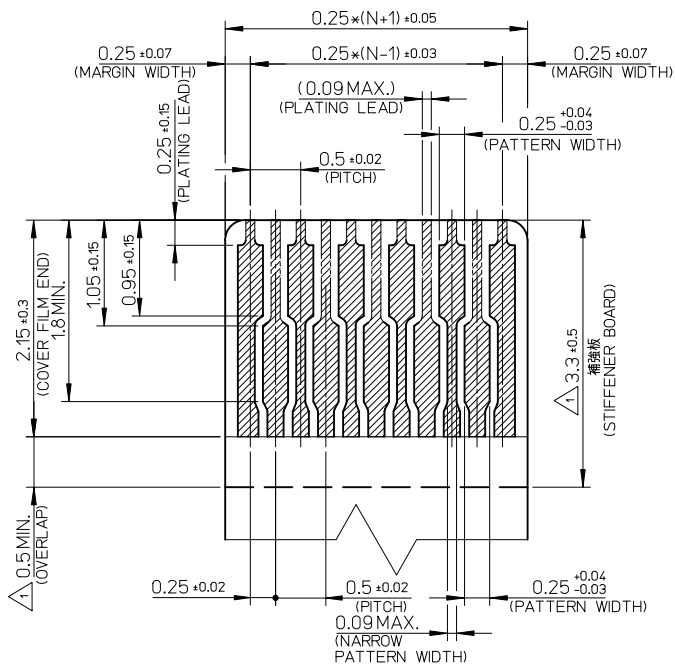
アクチュエータ開放位置
ACTUATOR OPENING POSITION

13.84	13	12	12.5	14.5	502078-5110	502078-5118	51
10.84	10	9	9.5	11.5	502078-3910	502078-3918	39
9.34	8.5	7.5	8	10	502078-3310	502078-3318	33
7.34	6.5	5.5	6	8	502078-2510	502078-2518	25
6.34	5.5	4.5	5	7	502078-2110	502078-2118	21
5.34	4.5	3.5	4	6	502078-1710	502078-1718	17
E	D	C	B	A	ORDER NO.	MATERIAL NO.	CKT.=N

REVISED EC NO: J2012-0409 DRAWN: TANAKA 2011/09/21 CHKD: APPR: SHOSHIKAWA 2011/09/30	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	20:1	METRIC	◎ □	
		10 UNDER	± ---	DRAWN BY	DATE	TITLE		0.25 PITCH FPC CONN E/O HGT=1.0 BTM CONTACT TYPE
		10 OVER 30 UNDER	± ---	YFUJITA	2008/12/15			
30 OVER	± ---	CHECKED BY	DATE	MOLEX INCORPORATED		DOCUMENT NO. SD-502078-003		
ANGULAR	±1 °	TKANEKO	2008/12/15	MATERIAL NO.			SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



FPC 構成材料例
EXAMPLE OF FPC COMPOSITION MATERIAL

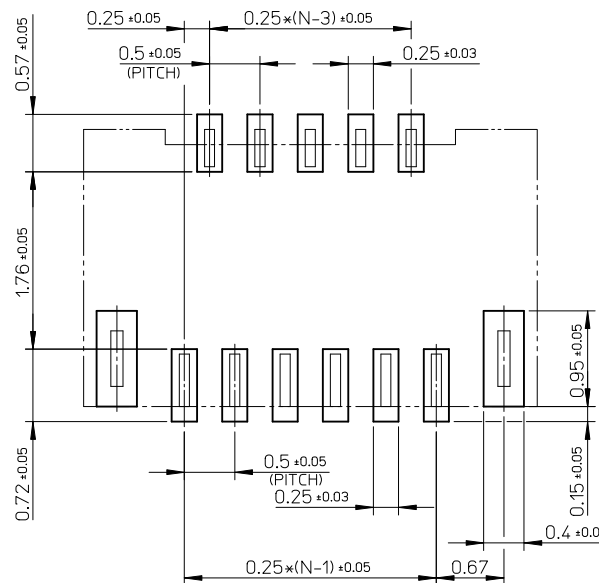


適合するFPC 推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(端子部仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)

注記 NOTES

- 補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を 0.5mm 以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT BE SECURED AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM
- 推奨ペースト厚 : 100μm
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100μm
RECOMMEND SCREEN OPEN RATIO : 80%



FPC挿入側
FPC INSERSION SIDE
参考基板レイアウト
RECOMMENDED PCB
PATTERN DIMENSIONS (REF.)

- FPCパターンのメッキ仕様は
金メッキ : 0.1μm 以上
下地ニッケルメッキ : 2~6μm
FPC PATTERN PLATING
GOLD PLATING : 0.1μm MINIMUM
NICKEL UNDER PLATING : 2~6μm

4 FPCについて (ABOUT FPC)

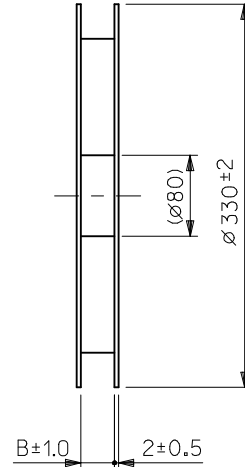
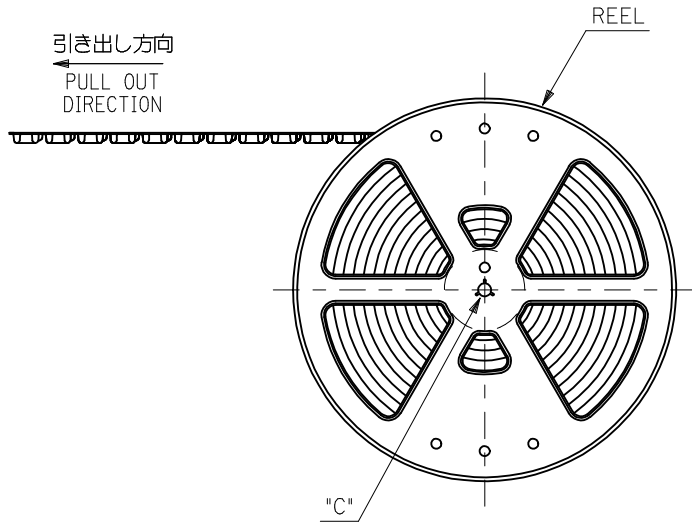
抜き方向は、導体側から補強板側を推奨します
補強板材質は、ポリイミドを推奨します
接着剤は熱硬化接着剤を推奨します
なお、接着剤の接点部への付着は導通不良の原因となりますので染み出しがないよう、お願いします
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
RECOMMENDED MATERIAL:
STIFFENER BOARD: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY

REVISED EC NO: J2012-04-09 DRWN: MTANAKA 2011/09/21 CHKD: APPR: SHOSHIKAWA 2011/09/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY YFUJITA	DATE 2008/12/15	TITLE 0.25 PITCH FPC CONN E/O HGT=1.0 BTM CONTACT TYPE	
	10 OVER 30 UNDER	± ---	CHECKED BY TKANEKO	DATE 2008/12/15	MOLEX INCORPORATED	
	30 OVER	± ---	APPROVED BY AHORINO	DATE 2008/12/15		
ANGULAR ±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1 OF 2	DOCUMENT NO. SD-502078-003	SHEET NO. 2 OF 2		
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

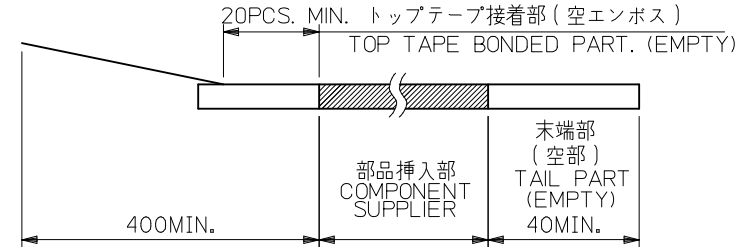
注記 NOTES

- 製品詳細寸法については図面 SD-502078-003 を参照下さい。
RE DETAILED DIMENSION, SEE SD-502078-003
- 梱包数量：3000 個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

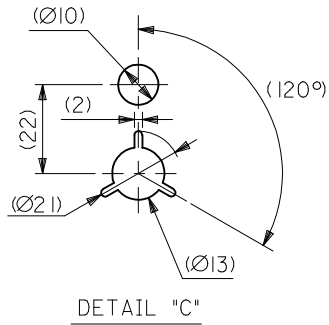
引き出し方向
PULL OUT
DIRECTION



引き出し方向
PULL OUT
DIRECTION

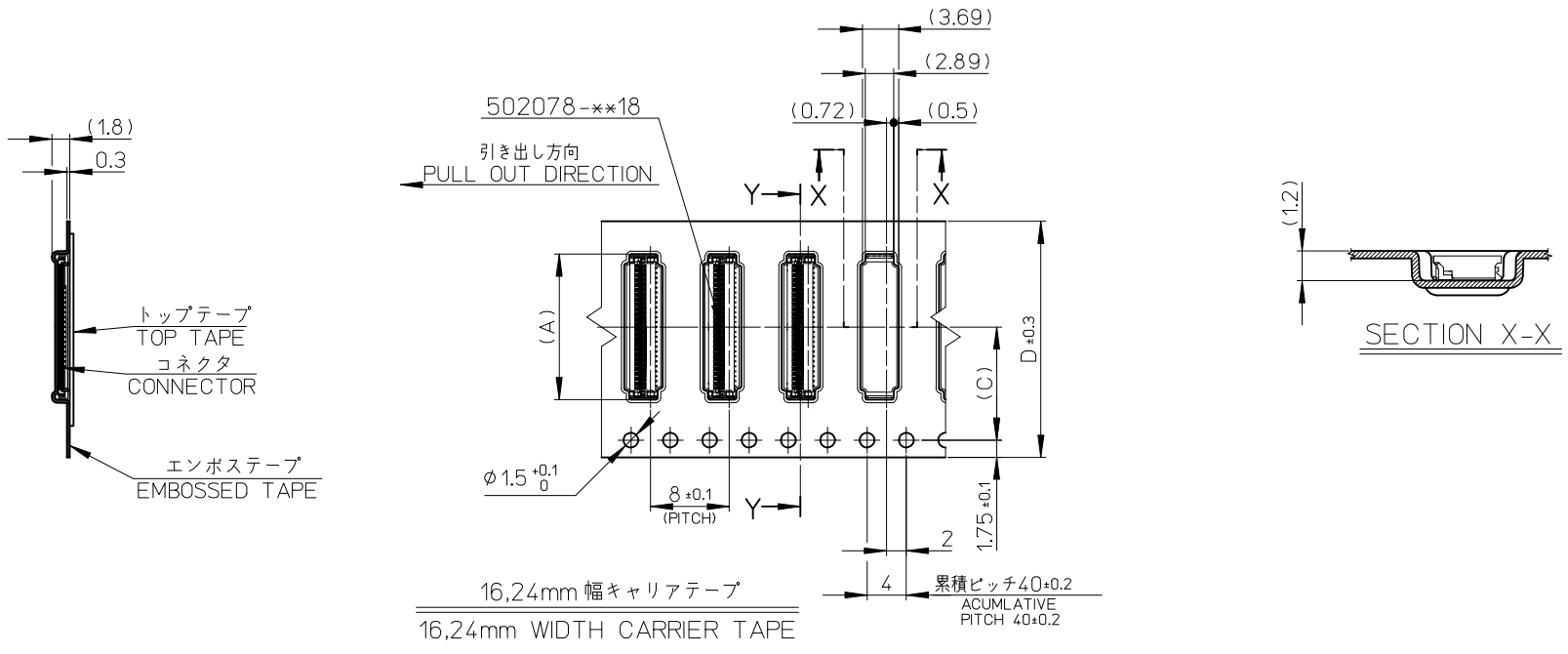


- 材料 MATERIAL
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE) : PET, PE, PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>



DETAIL "C"

RELEASED EC NO.: J2009-1529 DRWN: YFUJITA 2008/12/15 CHKD: TKANEKO 2008/12/15 APPR: TKANEKO 2008/12/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	MODEL NO. 502078-**10
	10 UNDER	±0.2	DRAWN BY YFUJITA	DATE 2008/12/15	TITLE 0.25 FPC CONN E/O HSG ASSY EMBOSSED TAPE PACKAGE		
	10 OVER 30 UNDER	±0.25	CHECKED BY TKANEKO	DATE 2008/12/15	MATERIAL NO. SEE CHART		
	30 OVER	±0.3	APPROVED BY AHORINO	DATE 2008/12/15	DOCUMENT NO. SD-502078-004		
	ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO. 1 OF 2		



24	11.5	25.4	14.8	502078-5110	51
			11.8	502078-3910	39
			10.3	502078-3310	33
			8.3	502078-2510	25
			7.3	502078-2110	21
16	7.5	17.4	6.3	502078-1710	17
D キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	製品番号 MATERIAL NO.	極数 CKT.
			MODEL NO. 502078-**-10		

RELEASED EC NO: J2009-1529 DRWN: YFUJITA 2008/12/15 CHKD: TKANEKO 2008/12/15 APPR: TKANEKO 2008/12/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER		±0.2	DRAWN BY YFUJITA		DATE 2008/12/15		TITLE 0.25MM FPC CONN E/O HSG ASSY EMBOSSED TAPE PACKAGE			
	10 OVER 30 UNDER		±0.25	CHECKED BY TKANEKO		DATE 2008/12/15		MOLEX INCORPORATED DOCUMENT NO. SD-502078-004 SHEET NO. 2 OF 2			
	30 OVER		±0.3	APPROVED BY AHORINO		DATE 2008/12/15					
	ANGULAR		±1 °	MATERIAL NO.		SEE CHART					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS											